

# SID

Factory: Rot am See

Article:

ML2

Provided:

Customer:

Date:

28.04.2026



**WÜRTH  
ELEKTRONIK**  
MORE THAN  
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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C-RS Panasonic R-F770-ED 18-50-00

50200950

18
50

VS



A-RAS-FR4-PP-106-H72-TG170-LowFlow-EM...

50203100

50
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2

A01

B-RaS-FR4-DS-1.194mm-018+018-TG150-HF...

50203144

0
1158
0

L2

3

A02

B00

L3

4

C-RAS-FR4-PP-106-H71-TG150-HF-EM-37B(...

50202996

94
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4

C-RAS-FR4-PP-106-H71-TG150-HF-EM-37B(...

50202996

0
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5

A-RS Kupferfolie-018my 330x490mm

50200238

18
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RS

6

Thickness after Pressing

B00:

 1440 µm

Tol+:

 155 µm

Tol-:

 155 µm

Dmax:

 1595 µm

Dmin:

 1285 µm

Thickness over all

 0 µm

Tol+:

 0 µm

Tol-:

 0 µm

Dmax:

 0 µm

Dmin:

 0 µm

Demand for customer

Thickness (D):

 1550 µm

Tol+:

 155 µm

Tol-:

 155 µm

Dmax:

 1705 µm

Dmin:

 1395 µm

Measuring point:

 (05) over SM and galv. Cu; both sides

nominal:

 1388 µm

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